	QUADRUPLE DIFFERENTIAL LINE RECEIV WITH 3-STATE OUTPU SLLS097C – JUNE 1980 – REVISED FEBRUARY 2
 Meets or Exceeds the Requirements of ANSI Standards EIA/TIA-422-B and EIA/TIA-422 B and ITH Becommendations 	D, N, OR NS PACKAGE (TOP VIEW)
EIA/TIA-423-B and ITU Recommendations V.10 and V.11	
• 3-State, TTL-Compatible Outputs	1A [] 2 15 [] 4B 1Y [] 3 14 [] 4A
Fast Transition Times	1,2EN [4 13] 4Y
 Operates From Single 5-V Supply Designed to Be Interchangeable With 	2Y [] 5 12 [] 3,4EN 2A [] 6 11 [] 3Y
Motorola™ MC3486	2B 🗍 7 10 🗍 3A
locarintian	GND [8 9] 3B

description

The MC3486 is a monolithic quadruple differential line receiver designed to meet the specifications of ANSI Standards TIA/EIA-422-B and TIA/EIA-423-B and ITU Recommendations V.10 and V.11. The MC3486 offers four independent differential-input line receivers that have TTL-compatible outputs. The outputs utilize 3-state circuitry to provide a high-impedance state at any output when the appropriate output enable is at a low logic level.

The MC3486 is designed for optimum performance when used with the MC3487 quadruple differential line driver. It is supplied in a 16-pin package and operates from a single 5-V supply.

The MC3486 is characterized for operation from 0°C to 70°C.

AVAILABLE OF HONS							
	PACKAGED DEVICES						
TA	PLASTIC SMALL OUTLINE (D, NS)	PLASTIC DIP (N)					
0°C to 70°C	MC3486D MC3486NS	MC3486N					

AVAILABLE OPTIONS

The D package is available taped and reeled. Add the suffix R to the device type (e.g., MC3486DR). The NS package is only available taped and reeled.



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MC3486

2002

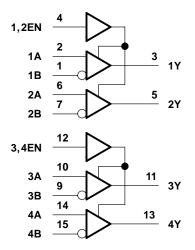
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FUNCTION TABLE (oach rocoivor)

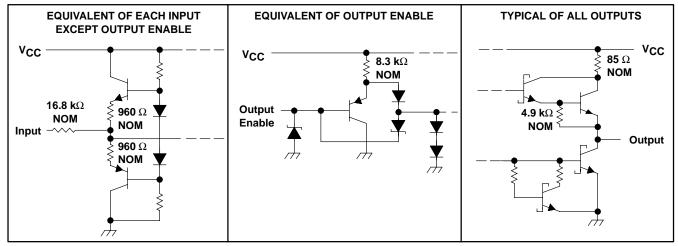
(each receiver)								
DIFFERENTIAL INPUTS A-B	ENABLE	OUTPUT Y						
$V_{ID} \le 0.2 V$	Н	Н						
$-0.2 \text{ V} < \text{V}_{\text{ID}} < 0.2 \text{ V}$	н	?						
$V_{ID} \leq -0.2 V$	н	L						
Irrelevant	L	Z						
Open	Н	?						

H = high level, L = low level, Z = high impedance (off),? = indeterminate

logic diagram (positive logic)



schematics of inputs and outputs





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC} (see Note 1)	8 V
Input voltage, V _I (A or B inputs)	±15 V
Differential input voltage, VID (see Note 2)	±25 V
Enable input voltage	
Low-level output current, I _{OI}	50 mA
Package thermal impedance, θ_{JA} (see Note 3): D package	73°C/W
N package	67°C/W
NS package	67°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{stg}	–65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential-input voltage, are with respect to network ground terminal.

2. Differential-input voltage is measured at the noninverting input with respect to the corresponding inverting input.

3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.75	5	5.25	V
VIC	Common-mode input voltage			±7	V
VID	Differential input voltage			±6	V
VIH	High-level enable input voltage	2			V
VIL	Low-level enable input voltage			0.8	V
Т _А	Operating free-air temperature	0		70	°C



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electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CONDITION	MIN	MAX	UNIT		
VIT+	Differential input high-threshold voltage	$V_{O} = 2.7 V$, $I_{O} = -0.4 mA$			0.2	V	
V_{IT-}	Differential input low-threshold voltage	$V_{O} = 0.5 V$, $I_{O} = -8 mA$		-0.2†		V	
VIK	Enable-input clamp voltage	I _I = -10 mA			-1.5	V	
Vон	High-level output voltage	$V_{ID} = 0.4 V$, $I_O = -0.4 mA$, See Note 4 and Figure 1		2.7		V	
V _{OL}	Low-level output voltage	$V_{ID} = -0.4 V$, $I_O = 8 mA$, See Note 4 and Figure 1			0.5	V	
1	High impodence state output ourrest	$V_{IL} = 0.8 V$, $V_{ID} = -3 V$,	V _O = 2.7 V		40		
I _{OZ} Hig	High-impedance-state output current	$V_{IL} = 0.8 V$, $V_{ID} = 3 V$,	V _O = 0.5 V		-40	μA	
			$V_{I} = -10 V$		-3.25		
	Differential input hiss summert	V _{CC} = 0 V or 5.25 V,	$V_{I} = -3 V$		-1.5	m A	
IВ	Differential-input bias current	Other inputs at 0 V	V _I = 3 V		1.5	.5 mA	
			V _I = 10 V		3.25		
I	High lovel enable input ourrent	VI = 5.25 V		100			
I _{IH} High-level enable input current		VI = 2.7 V		20	μA		
۱ _{۱L}	Low-level enable input current	$V_{I} = -0.5 V$			-100	μA	
los	Short-circuit output current	$V_{\text{ID}} = 3 \text{ V}, \qquad \qquad V_{\text{O}} = 0,$	See Note 5	-15	-100	mA	
ICC	Supply current	$V_{IL} = 0$			85	mA	

[†] The algebraic convention, in which the least positive (most negative) limit is designated as minimum, is used in this data sheet for threshold voltages only.

NOTES: 4. Refer to ANSI Standards TIA/EIA-422-B and TIA/EIA-423-B for exact conditions.

5. Only one output should be shorted at a time.

switching characteristics, V_{CC} = 5 V, C_L = 15 pF, T_A = 25°C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
^t PHL	Propagation delay time, high- to low-level output	See Figure 2		28	35	ns
^t PLH	Propagation delay time, low- to high-level output	See Figure 2		27	30	ns
^t PZH	Output enable time to high level			13	30	ns
^t PZL	Output enable time to low level	See Figure 3		20	30	ns
^t PHZ				26	35	ns
^t PLZ	Output disable time from low level			27	35	ns



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PARAMETER MEASUREMENT INFORMATION

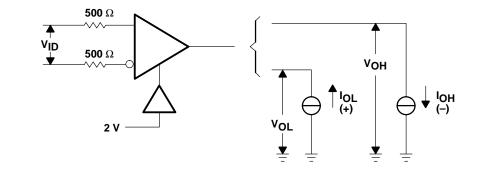
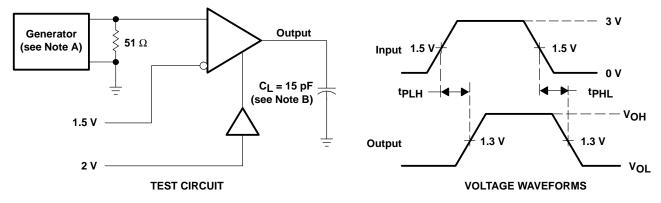


Figure 1. VOH, VOL

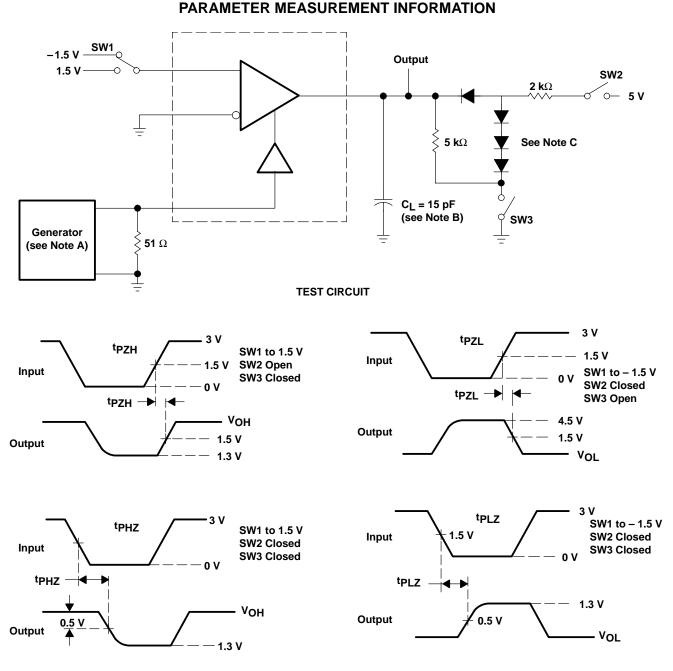


- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, duty cycle = 50%, t_r \leq 6 ns, $t_f \le 6 \text{ ns.}$
 - B. CL includes probe and stray capacitance.

Figure 2. Test Circuit and Voltage Waveforms

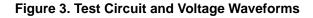


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NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, duty cycle = 50%, t_f \leq 6 ns, t_f \leq 6 ns.

- B. C_L includes probe and stray capacitance.
- C. All diodes are 1N916 or equivalent.







24-Aug-2018

PACKAGING INFORMATION

Orderable Device	Status	Package Type	•	Pins	•	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
MC3486D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MC3486	Samples
MC3486DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MC3486	Samples
MC3486DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MC3486	Samples
MC3486DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MC3486	Samples
MC3486DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MC3486	Samples
MC3486N	ACTIVE	PDIP	Ν	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	MC3486N	Samples
MC3486NE4	ACTIVE	PDIP	Ν	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	MC3486N	Samples
MC3486NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MC3486	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



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PACKAGE OPTION ADDENDUM

24-Aug-2018

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MC3486DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
MC3486NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

26-Jan-2013



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MC3486DR	SOIC	D	16	2500	333.2	345.9	28.6
MC3486NSR	SO	NS	16	2000	367.0	367.0	38.0

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



4211283-4/E 08/12

D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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